

Title (en)

DIODE WITH LEAD TERMINAL FOR SOLAR CELL

Title (de)

DIODE MIT ANSCHLUSSLEITUNGS-ABSCHLUSS FÜR EINE SOLARZELLE

Title (fr)

DIODE AVEC BORNE DE SORTIE POUR CELLULE SOLAIRE

Publication

EP 1753033 A4 20070801 (EN)

Application

EP 05741613 A 20050519

Priority

- JP 2005009156 W 20050519
- JP 2004149057 A 20040519

Abstract (en)

[origin: EP1753033A1] The object of the present invention is to provide a diode that acts as a cell string bypass diode or a reverse-current preventive diode, has excellent heat dissipativity, and are preferably sealed integrally in a solar cell module. An N terminal 11 has an N substrate part 12 having an even thickness of 0.8 mm or more, an N thin part 13, which is one thin part, and an N connecting wire receiving part 14, which is the other thin part. A P terminal 21 has a P substrate part 22, a P thin part 23, and a P connecting wire receiving part 24. In a state where said diode chip 31 is connected, the thickness of the entire lead terminal is almost the same as that of the substrate part, i.e. the terminal, and the total of plane area of the N substrate part and that of the P substrate part is 200 mm² or more. Said diode, together with the solar cell, is sealed between a front surface material and a rear surface material where the solar cell is to be sealed.

IPC 8 full level

H01L 31/042 (2006.01); **H01L 27/142** (2006.01)

CPC (source: EP US)

H01L 27/142 (2013.01 - EP US); **H01L 31/044** (2014.12 - EP US); **Y02E 10/50** (2013.01 - EP US)

Citation (search report)

No further relevant documents disclosed

Cited by

US2013340812A1; EP3252946A1; EP2077579A4; EP2226850A1; EP3252945A1; US8237065B2; WO2010057978A1

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DOCDB simple family (publication)

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